/ Descriptions

Silicon NPN transistor in a SOT-23 Plastic Package.

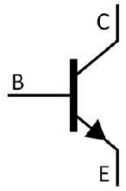
/ Features

High voltage, complementary pair with BC857.

/ Applications

General purpose application and switching application.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Emitter PIN 3 Collector

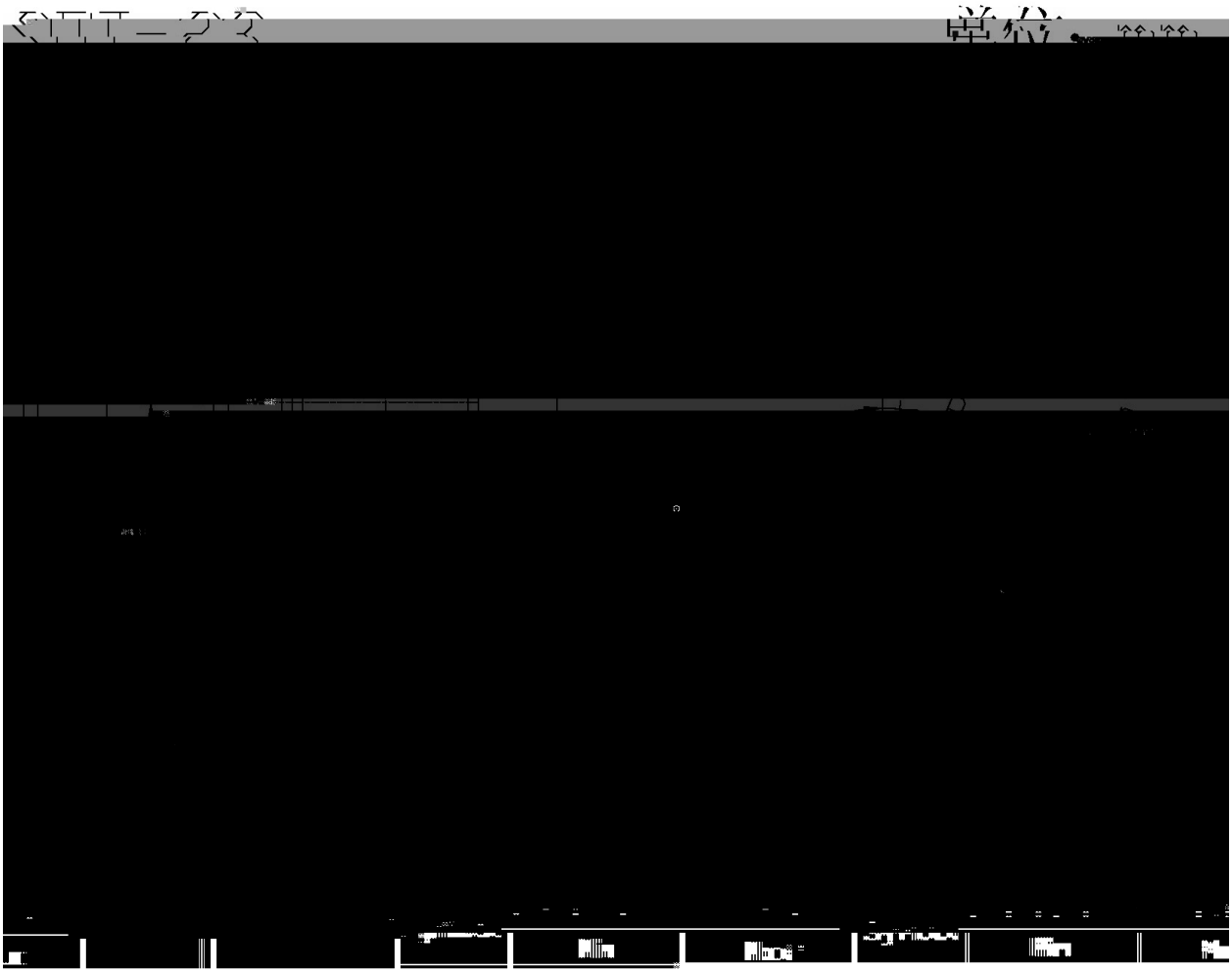
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	A	B	C
h_{FE} Range			

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	45	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current - Continuous	I_C	100	mA
Collector Power Dissipation	P_C	350	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	V_{CB}=30V I_E=0			0.015	μA
DC Current Gain	h_{FE}	V_{CE}=5.0V I_C=2.0mA	110		800	
Collector to Emitter Saturation Voltage	$V_{CE(sat)1}$	I_C=10mA I_B=0.5mA		0.09	0.25	V
	$V_{CE(sat)2}$	I_C=100mA I_B=5.0mA		0.2	0.6	V
Base to Emitter Saturation Voltage	$V_{BE(sat)1}$	I_C=10mA I_B=0.5mA		0.7		V
	$V_{BE(sat)2}$	I_C=100mA I_B				

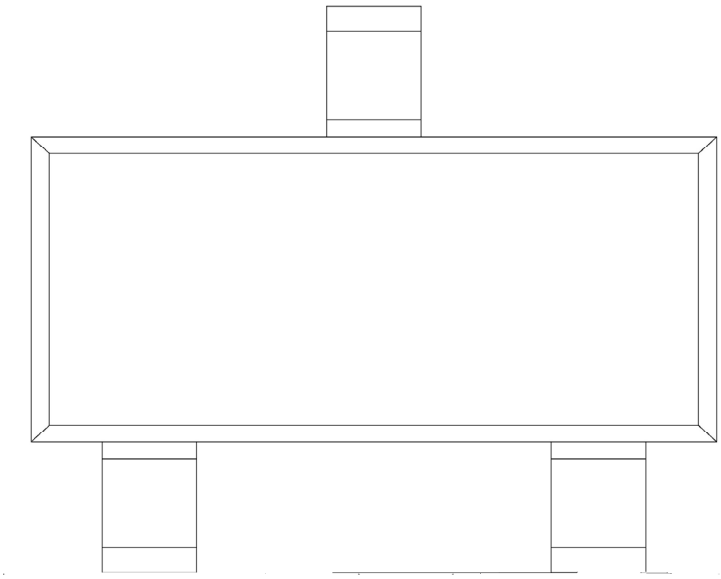
/ Package Dimensions



7°				

E1	0.85	1.05	P	
b	0.35	0.55		

/ Marking Instructions

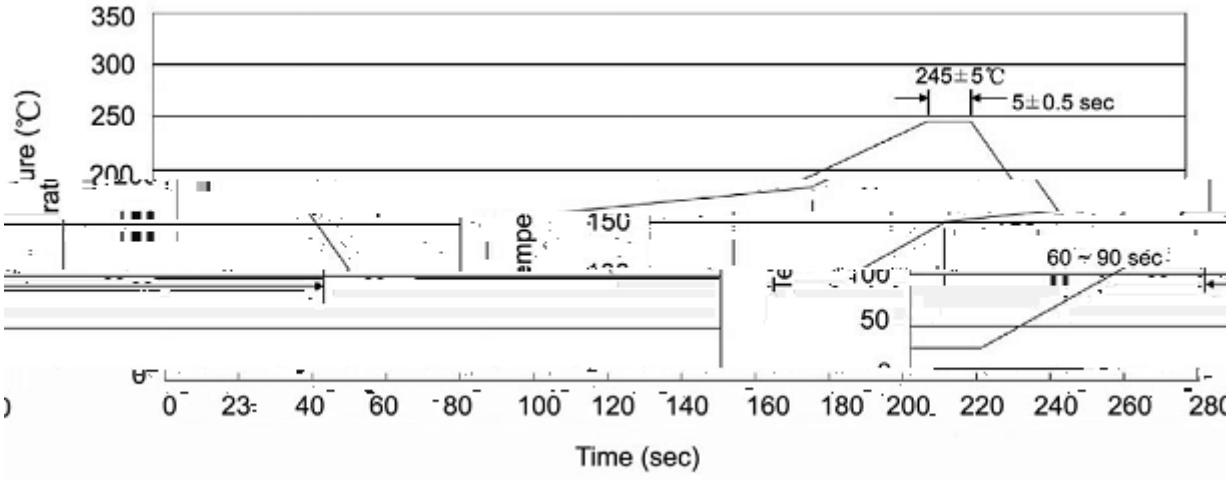


Note:

H: Company Code

1E: Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245 5 5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	39×385×205

/ Notices